то:	文件编号	HXA-L52-12(01)
10.	发行日期	2020年10月18日

# 承 认 规 格 书

种 类: <u>SMD Power Choke Coil</u>

系列号: <u>HXTP1205H-R33M</u>

客户料号:\_\_\_\_\_

客	子 承 认 栏	
承 认 日 期	年  月	日

(贵司承认后请签署一份返回艾申迪电子, 谢谢!)

## 厦门艾申迪电子有限公司技术质量部

承 认	确 认	作 成
龙梅	梁峰	王亮

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ECN HISTORY LIST								
REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWN			
1.0	20/10/18	新發行	龙梅	梁峰	王亮			
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### 1. Features

- 1. High current, low DCR, high efficiency.
- 2.100% Lead (Pb)-Free and RoHS compliant.
- $3.14.0 \times 12.9 \times 6.5 \text{mm}$  maximum surface mount package
- 4. Operating temperature -40  $^{\circ}\text{C} \text{~~+} 125 ^{\circ}\text{C}$  (Including self temperature rise)

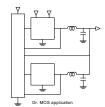




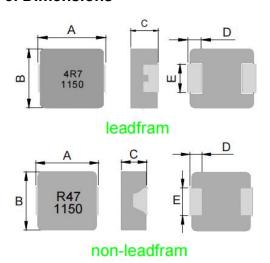
## 2. Applications

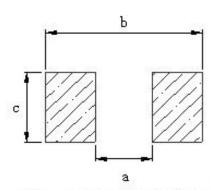
Note PC power system.

DC/DC converter.



### 3. Dimensions

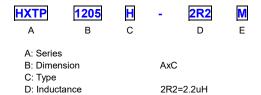




Recommend Land Pattern

Series	Туре	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	a (mm)	b (mm)	c (mm)
LIVEDAGGELL	leadframe	40 5:00	10.5.00				0.0	110	<b>5</b> 0
HXTP1205H	Non-leadframe	13. 5±0.3	12.5±0.3	4.8±0.3	2.3±0.3	4.7±0.3	8.0	14.2	5.0

### 4. Part Numbering



M=±20%

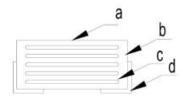
## 5. Specification

E: Inductance Tolerance

Part Number	Inductance L0 (uH)±20% @ 0 A	I sat (A) Typ.	I rms (A) Typ	DCR (mΩ) Typ. @25°C	DCR (mΩ) Max. @25°C	Тур
HXTP1205H-R33M	0.33	80	42	0.7	0.9	Non-leadframe

## 6. Material List





NO	Items	Materials
1	Marking	Ink(black)
2	Core	Carbonyl Powder
3	Wire	Polyester Wire or equivalent
4	Terminal	Copper plated with Sn

## 7. Reliability and Test Condition

Item	Specification and Requirement	Test Method		
Solderability	No case deformation or change in apperarance     New solder coverage More than 95%	1.Preheat: 155°C±5°C , 60S±2S 2.Tin: lead-free. 3.Temperature:240°C±5°C , flux 3.0S±0.5S.		
Mechanical shock	No case deformation or change in apperarance     △L/Lo≤±10%	Acceleration: 100G     Pulse time:: 6ms     3. 3 times in each positive and negative direction of mutual perpendicular directions		
Mechanical vibration	No case deformation or change in apperarance     △L/Lo≤±10%	1. Reflow: 2times 2. Frequency: 10HZ~55HZ~10HZ, 20 Min/Cycles 3. Amplitude: 1.52 mm 4. Directions: X,Y,Z 5. Time: 12 cycle / direction		
Endurance Relia	bility			
Item	Specification and Requirement	Test Method		
Thermal Shock	Inductance change: Within ± 10% Without distinct damage in appearance	1. First -40°C for 30 minutes, last 125°C for 30 minute as 1 cycle. Go through 1000 cycles.  2. Max transfer time is 3 minutes.  3. Measured at room temperature after placing for 24 ± 2 hours.		
Humidity Resistance	Inductance change: Within ± 10% Without distinct damage in appearance	1.Reflow 2 times, 2.85°C,85%RH,1000 hours 3.Measured at room temperature after placing for 24±2 hours		
Low temperature storage	Inductance change: Within ± 10% Without distinct damage in appearance	Temperature: -40 ± 2℃     Time: 1000 hours     Measured at room temperature after placing for 24 ± 2 hours		
High Inductance change: temperature Within ± 10% Without distinct damage in appearance		1. Temperature: +125 ± 2°C 2. Time: 1000 hours 3. Measured at room temperature after placing for 24±2 hours		

### 8. Soldering and Mounting

## **Recommended Soldering Technologies**

### (1)Re-flowing Profile

Preheat condition: 150 ~200 ℃/60~180sec.

Allowed time above 217 °C: 80~120sec.

Max temp: 260°C

Max time at max temp: 10 sec.

Solder paste: Sn/3.0Ag/0.5Cu

Allowed Reflow time: 2x max

## (2)Iron Soldering Profile

Iron soldering power: Max. 30W

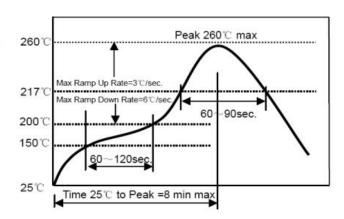
Pre-heating: 150 ℃/60sec.

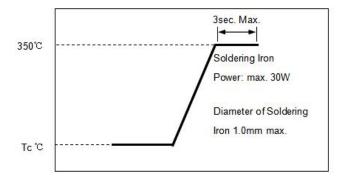
Soldering Tip temperature: 350℃ Max.

Soldering time: 3sec. Max.

Solder paste: Sn/3.0Ag/0.5Cu

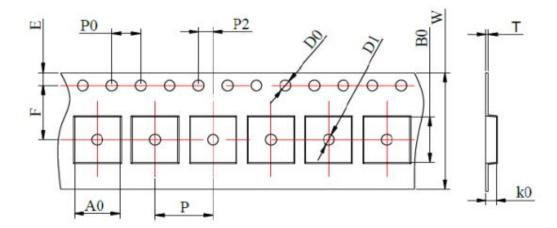
Max.1 times for iron soldering





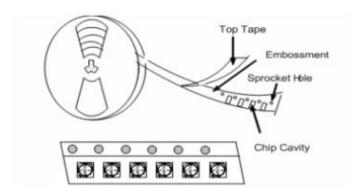
## 9. Packaging Information

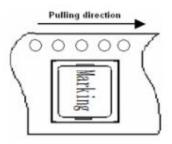
### (1) Tape Packaging Dimensions (Unit: mm)



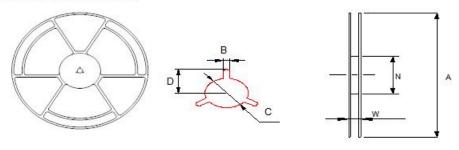
Tape dimensions (mm)											
W	Р	P0	P2	D0	D1	Т	A0	В0	K0	E	F
24 ± 0.3	16 ± 0.1	4.0 ± 0.1	2.0 ± 0.1	1.5 ± 0.1	1.5 ± 0.1	0.5 ± 0.05	13.1 ± 0.1	14 ± 0.1	6.8 ± 0.1	1.75 ± 0.1	11.5 ± 0.1

### Taping Drawings (UNIT:mm)





### (2) Reel Dimensions (Unit: mm)

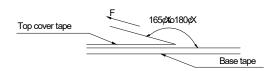


A	w	N	В	С	D
330+2.0	24±0.5	97± 0.5	2.2+0.5	13.0 ± 0.2	10.75 ± 0.25

#### (3) Packaging Quantity

НХТР	1205
Chip / Reel	500

#### (4) Tearing Off Force



The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions(referenced ANSI/EIA-481-C-2003 of 4.11 standard).

Room Temp.	Room Humidity	Room atm	Tearing Speed
(℃)	(%)	(hPa)	mm/min
5~35	45~85	860~1060	300

#### **Application Notice**

·Storage Conditions (component level)

To maintain the solderability of terminal electrodes:

- 1. ASDI products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
- 2. Temperature and humidity conditions: Less than 40°C and 60% RH.
- 3. Recommended products should be used within 12 months form the time of delivery.
  4. The packaging material should be kept where no chlorine or sulfur exists in the air.

·Transportation

- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
   The use of tweezers or vacuum pick up is strongly recommended for individual components.
- 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

## 单击下面可查看定价,库存,交付和生命周期等信息

## >>ISND(华信安)